



Global IC Package Substrates Market by Size, by Type, by Application, by Region, History and Forecast 2021-2032

Industry	Published	Pages	Format
Electronics & Semiconductor	2025-12-22	193	PDF

Single User	Multi User	Enterprise
USD 3,950	USD 5,925	USD 7,900

Description

The global IC Package Substrates market is projected to grow from US\$ million in 2026 to US\$ million by 2032, implying a CAGR of % over 2026-2032.

The US & Canada market for IC Package Substrates is projected to increase from US\$ million in 2026 to US\$ million by 2032, at a CAGR of % over 2026-2032.

The Europe market for IC Package Substrates is projected to increase from US\$ million in 2026 to US\$ million by 2032, at a CAGR of % over 2026-2032.

The Asia Pacific market for IC Package Substrates is projected to increase from US\$ million in 2026 to US\$ million by 2032, at a CAGR of % over 2026-2032.

The China market for IC Package Substrates is projected to increase from US\$ million in 2026 to US\$ million by 2032, at a CAGR of % over 2026-2032.

Leading global manufacturers of IC Package Substrates include Unimicron, Ibiden, Nan Ya PCB, Shinko Electric Industries, Kinsus Interconnect Technology, AT&S, Semco, Kyocera and TOPPAN, among others. In 2025, the top three vendors together accounted for approximately % of global revenue.

On the production side, the report examines IC Package Substrates output, growth rates, and market shares by manufacturer and by region (at regional and country level) for 2021-2026, with forecasts through 2032.

On the consumption side, the report analyzes sales of IC Package Substrates by region (regional and country level), company, type, and application for 2021-2026 and provides forecasts through 2032.

The report provides an overview of the global IC Package Substrates market in terms of capacity, output, revenue, and price, analyzing global market trends using historical revenue and sales data for 2021-2025, estimates for 2026, and projected CAGRs through 2032.

The study covers key producers of IC Package Substrates and consumption patterns in major regions and countries, assesses future market potential, and highlights priority regions and countries for segmenting the market into sub-sectors, with country-specific market value data for the U.S., Canada, Mexico, Brazil, China, Japan, South Korea, Southeast Asia, India, Germany, the U.K., Italy, the Middle East, Africa, and other countries.

The report also presents IC Package Substrates sales, revenue, market share, and industry ranking for the main manufacturers for 2021-2026, identifies the major stakeholders in the global market, and analyzes their competitive landscape and market positioning based on recent developments and segmental revenues.

In addition, the report analyzes segment data by type and application—covering sales, revenue, and price—for 2021-2032, and evaluates and forecasts the IC Package Substrates market size, projected growth trends, production technologies, key applications, and end-use industries.

IC Package Substrates Segment by Company

- Unimicron
- Ibiden
- Nan Ya PCB
- Shinko Electric Industries
- Kinsus Interconnect Technology
- AT&S
- Semco
- Kyocera
- TOPPAN
- Zhen Ding Technology
- Daeduck Electronics
- ASE Material
- LG InnoTek
- Simmtech
- Shennan Circuit
- Shenzhen Fastprint Circuit Tech
- ACCESS
- Suntak Technology
- National Center for Advanced Packaging (NCAP China)
- Huizhou China Eagle Electronic Technology
- DSBJ
- Shenzhen Kinwong Electronic
- AKM Meadville
- Victory Giant Technology

IC Package Substrates Segment by Type

- FC-BGA
- FC-CSP
- WB BGA
- WB CSP
- RF Module
- Others

IC Package Substrates Segment by Application

- Smart Phone
- PC (tablet and Laptop)
- Wearable Device
- Others

IC Package Substrates Segment by Region

- North America
- United States
- Canada
- Mexico
- Europe
- Germany
- France
- U.K.

Italy
Russia
Spain
Netherlands
Switzerland
Sweden
Poland
Asia-Pacific
China
Japan
South Korea
India
Australia
Taiwan
Southeast Asia
South America
Brazil
Argentina
Chile
Middle East & Africa
Egypt
South Africa
Israel
Türkiye
GCC Countries

Study Objectives

1. To analyze and research the global status and future forecast, involving, production, value, consumption, growth rate (CAGR), market share, historical and forecast.
2. To present the key manufacturers, capacity, production, revenue, market share, and Recent Developments.
3. To split the breakdown data by regions, type, manufacturers, and Application.
4. To analyze the global and key regions market potential and advantage, opportunity and challenge, restraints, and risks.
5. To identify significant trends, drivers, influence factors in global and regions.
6. To analyze competitive developments such as expansions, agreements, new product launches, and acquisitions in the market.

Reasons to Buy This Report

1. This report will help the readers to understand the competition within the industries and strategies for the competitive environment to enhance the potential profit. The report also focuses on the competitive landscape of the global IC Package Substrates market, and introduces in detail the market share, industry ranking, competitor ecosystem, market performance, new product development, operation situation, expansion, and acquisition. etc. of the main players, which helps the readers to identify the main competitors and deeply understand the competition pattern of the market.
2. This report will help stakeholders to understand the global industry status and trends of IC Package Substrates and provides them with information on key market drivers, restraints, challenges, and opportunities.
3. This report will help stakeholders to understand competitors better and gain more insights to strengthen their position in their businesses. The competitive landscape section includes the market share and rank (in volume and value), competitor ecosystem, new product development, expansion, and acquisition.
4. This report stays updated with novel technology integration, features, and the latest developments in the market.

5. This report helps stakeholders to gain insights into which regions to target globally.
6. This report helps stakeholders to gain insights into the end-user perception concerning the adoption of IC Package Substrates.
7. This report helps stakeholders to identify some of the key players in the market and understand their valuable contribution.

Chapter Outline

Chapter 1:

Provides an overview of the IC Package Substrates market, including product definition, global market growth prospects, production value, capacity, and average price forecasts (2021-2032).

Chapter 2:

Analysis key trends, drivers, challenges, and opportunities within the global IC Package Substrates industry.

Chapter 3:

Detailed analysis of IC Package Substrates market competition landscape. Including IC Package Substrates manufacturers' output value, output and average price from 2021 to 2026, as well as competition analysis indicators such as origin, product type, application, merger and acquisition information, etc.

Chapter 4:

Provides the analysis of various market segments by type, covering the market size and development potential of each market segment, to help readers find the blue ocean market in different market segments.

Chapter 5:

Provides the analysis of various market segments by application, covering the market size and development potential of each market segment, to help readers find the blue ocean market in different downstream markets.

Chapter 6:

Provides profiles of key players, introducing the basic situation of the main companies in the market in detail, including product production/output, value, price, gross margin, product introduction, recent development, etc.

Chapter 7:

Production/Production Value of IC Package Substrates by region. It provides a quantitative analysis of the market size and development potential of each region in the next six years.

Chapter 8:

Consumption of IC Package Substrates in regional level and country level. It provides a quantitative analysis of the market size and development potential of each region and its main countries and introduces the market development, future development prospects, market space, and production of each country in the world.

Chapter 9:

Analysis of industrial chain, including the upstream and downstream of the industry.

Chapter 10:

Concluding Insights of the report.

Table of Contents

1 Market Overview

- 1.1 Product Definition
- 1.2 Global Market Growth Prospects
 - 1.2.1 Global IC Package Substrates Production Value Estimates and Forecasts (2021-2032)
 - 1.2.2 Global IC Package Substrates Production Capacity Estimates and Forecasts (2021-2032)
 - 1.2.3 Global IC Package Substrates Production Estimates and Forecasts (2021-2032)
 - 1.2.4 Global IC Package Substrates Market Average Price (2021-2032)
- 1.3 Assumptions and Limitations
- 1.4 Study Goals and Objectives

2 Global IC Package Substrates Market Dynamics

- 2.1 IC Package Substrates Industry Trends
- 2.2 IC Package Substrates Industry Drivers
- 2.3 IC Package Substrates Industry Opportunities and Challenges
- 2.4 IC Package Substrates Industry Restraints

3 IC Package Substrates Market by Manufacturers

- 3.1 Global IC Package Substrates Production Value by Manufacturers (2021-2026)
- 3.2 Global IC Package Substrates Production by Manufacturers (2021-2026)
- 3.3 Global IC Package Substrates Average Price by Manufacturers (2021-2026)
- 3.4 Global IC Package Substrates Industry Manufacturers Ranking, 2024 VS 2025 VS 2026
- 3.5 Global IC Package Substrates Key Manufacturers Manufacturing Sites & Headquarters
- 3.6 Global IC Package Substrates Manufacturers, Product Type & Application
- 3.7 Global IC Package Substrates Manufacturers Established Date
- 3.8 Market Competitive Analysis
 - 3.8.1 Global IC Package Substrates Market CR5 and HHI
 - 3.8.2 Global Top 5 and 10 IC Package Substrates Players Market Share by Production Value in 2025
 - 3.8.3 2025 IC Package Substrates Tier 1, Tier 2, and Tier 3

4 IC Package Substrates Market by Type

- 4.1 IC Package Substrates Type Introduction
 - 4.1.1 FC-BGA
 - 4.1.2 FC-CSP
 - 4.1.3 WB BGA
 - 4.1.4 WB CSP
 - 4.1.5 RF Module
 - 4.1.6 Others
 - 4.2 Global IC Package Substrates Production by Type
 - 4.2.1 Global IC Package Substrates Production by Type (2021 VS 2025 VS 2032)
 - 4.2.2 Global IC Package Substrates Production by Type (2021-2032)
 - 4.2.3 Global IC Package Substrates Production Market Share by Type (2021-2032)
 - 4.3 Global IC Package Substrates Production Value by Type
 - 4.3.1 Global IC Package Substrates Production Value by Type (2021 VS 2025 VS 2032)
 - 4.3.2 Global IC Package Substrates Production Value by Type (2021-2032)
 - 4.3.3 Global IC Package Substrates Production Value Market Share by Type (2021-2032)
-

5 IC Package Substrates Market by Application

5.1 IC Package Substrates Application Introduction

5.1.1 Smart Phone

5.1.2 PC (tablet and Laptop)

5.1.3 Wearable Device

5.1.4 Others

5.2 Global IC Package Substrates Production by Application

5.2.1 Global IC Package Substrates Production by Application (2021 VS 2025 VS 2032)

5.2.2 Global IC Package Substrates Production by Application (2021-2032)

5.2.3 Global IC Package Substrates Production Market Share by Application (2021-2032)

5.3 Global IC Package Substrates Production Value by Application

5.3.1 Global IC Package Substrates Production Value by Application (2021 VS 2025 VS 2032)

5.3.2 Global IC Package Substrates Production Value by Application (2021-2032)

5.3.3 Global IC Package Substrates Production Value Market Share by Application (2021-2032)

6 Company Profiles

6.1 Unimicron

6.1.1 Unimicron Company Information

6.1.2 Unimicron Business Overview

6.1.3 Unimicron IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.1.4 Unimicron IC Package Substrates Product Portfolio

6.1.5 Unimicron Recent Developments

6.2 Ibiden

6.2.1 Ibiden Company Information

6.2.2 Ibiden Business Overview

6.2.3 Ibiden IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.2.4 Ibiden IC Package Substrates Product Portfolio

6.2.5 Ibiden Recent Developments

6.3 Nan Ya PCB

6.3.1 Nan Ya PCB Company Information

6.3.2 Nan Ya PCB Business Overview

6.3.3 Nan Ya PCB IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.3.4 Nan Ya PCB IC Package Substrates Product Portfolio

6.3.5 Nan Ya PCB Recent Developments

6.4 Shinko Electric Industries

6.4.1 Shinko Electric Industries Company Information

6.4.2 Shinko Electric Industries Business Overview

6.4.3 Shinko Electric Industries IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.4.4 Shinko Electric Industries IC Package Substrates Product Portfolio

6.4.5 Shinko Electric Industries Recent Developments

6.5 Kinsus Interconnect Technology

6.5.1 Kinsus Interconnect Technology Company Information

6.5.2 Kinsus Interconnect Technology Business Overview

6.5.3 Kinsus Interconnect Technology IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.5.4 Kinsus Interconnect Technology IC Package Substrates Product Portfolio

6.5.5 Kinsus Interconnect Technology Recent Developments

6.6 AT&S

6.6.1 AT&S Company Information

6.6.2 AT&S Business Overview

6.6.3 AT&S IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.6.4 AT&S IC Package Substrates Product Portfolio

6.6.5 AT&S Recent Developments

6.7 Semco

6.7.1 Semco Company Information

6.7.2 Semco Business Overview

6.7.3 Semco IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.7.4 Semco IC Package Substrates Product Portfolio

6.7.5 Semco Recent Developments

6.8 Kyocera

6.8.1 Kyocera Company Information

6.8.2 Kyocera Business Overview

6.8.3 Kyocera IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.8.4 Kyocera IC Package Substrates Product Portfolio

6.8.5 Kyocera Recent Developments

6.9 TOPPAN

6.9.1 TOPPAN Company Information

6.9.2 TOPPAN Business Overview

6.9.3 TOPPAN IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.9.4 TOPPAN IC Package Substrates Product Portfolio

6.9.5 TOPPAN Recent Developments

6.10 Zhen Ding Technology

6.10.1 Zhen Ding Technology Company Information

6.10.2 Zhen Ding Technology Business Overview

6.10.3 Zhen Ding Technology IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.10.4 Zhen Ding Technology IC Package Substrates Product Portfolio

6.10.5 Zhen Ding Technology Recent Developments

6.11 Daeduck Electronics

6.11.1 Daeduck Electronics Company Information

6.11.2 Daeduck Electronics Business Overview

6.11.3 Daeduck Electronics IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.11.4 Daeduck Electronics IC Package Substrates Product Portfolio

6.11.5 Daeduck Electronics Recent Developments

6.12 ASE Material

6.12.1 ASE Material Company Information

6.12.2 ASE Material Business Overview

6.12.3 ASE Material IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.12.4 ASE Material IC Package Substrates Product Portfolio

6.12.5 ASE Material Recent Developments

6.13 LG InnoTek

6.13.1 LG InnoTek Company Information

6.13.2 LG InnoTek Business Overview

6.13.3 LG InnoTek IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.13.4 LG InnoTek IC Package Substrates Product Portfolio

6.13.5 LG InnoTek Recent Developments

6.14 Simmtech

6.14.1 Simmtech Company Information

6.14.2 Simmtech Business Overview

6.14.3 Simmtech IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.14.4 Simmtech IC Package Substrates Product Portfolio

6.14.5 Simmtech Recent Developments

6.15 Shennan Circuit

6.15.1 Shennan Circuit Company Information

6.15.2 Shennan Circuit Business Overview

6.15.3 Shennan Circuit IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.15.4 Shennan Circuit IC Package Substrates Product Portfolio

6.15.5 Shennan Circuit Recent Developments

6.16 Shenzhen Fastprint Circuit Tech

6.16.1 Shenzhen Fastprint Circuit Tech Company Information

6.16.2 Shenzhen Fastprint Circuit Tech Business Overview

6.16.3 Shenzhen Fastprint Circuit Tech IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.16.4 Shenzhen Fastprint Circuit Tech IC Package Substrates Product Portfolio

6.16.5 Shenzhen Fastprint Circuit Tech Recent Developments

6.17 ACCESS

6.17.1 ACCESS Company Information

6.17.2 ACCESS Business Overview

6.17.3 ACCESS IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.17.4 ACCESS IC Package Substrates Product Portfolio

6.17.5 ACCESS Recent Developments

6.18 Suntak Technology

6.18.1 Suntak Technology Company Information

6.18.2 Suntak Technology Business Overview

6.18.3 Suntak Technology IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.18.4 Suntak Technology IC Package Substrates Product Portfolio

6.18.5 Suntak Technology Recent Developments

6.19 National Center for Advanced Packaging (NCAP China)

6.19.1 National Center for Advanced Packaging (NCAP China) Company Information

6.19.2 National Center for Advanced Packaging (NCAP China) Business Overview

6.19.3 National Center for Advanced Packaging (NCAP China) IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.19.4 National Center for Advanced Packaging (NCAP China) IC Package Substrates Product Portfolio

6.19.5 National Center for Advanced Packaging (NCAP China) Recent Developments

6.20 Huizhou China Eagle Electronic Technology

6.20.1 Huizhou China Eagle Electronic Technology Company Information

6.20.2 Huizhou China Eagle Electronic Technology Business Overview

6.20.3 Huizhou China Eagle Electronic Technology IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.20.4 Huizhou China Eagle Electronic Technology IC Package Substrates Product Portfolio

6.20.5 Huizhou China Eagle Electronic Technology Recent Developments

6.21 DSBJ

6.21.1 DSBJ Company Information

6.21.2 DSBJ Business Overview

6.21.3 DSBJ IC Package Substrates Production, Value and Gross Margin (2021-2026)

6.21.4 DSBJ IC Package Substrates Product Portfolio

6.21.5 DSBJ Recent Developments

- 6.22 Shenzhen Kinwong Electronic
 - 6.22.1 Shenzhen Kinwong Electronic Company Information
 - 6.22.2 Shenzhen Kinwong Electronic Business Overview
 - 6.22.3 Shenzhen Kinwong Electronic IC Package Substrates Production, Value and Gross Margin (2021-2026)
 - 6.22.4 Shenzhen Kinwong Electronic IC Package Substrates Product Portfolio
 - 6.22.5 Shenzhen Kinwong Electronic Recent Developments
- 6.23 AKM Meadville
 - 6.23.1 AKM Meadville Company Information
 - 6.23.2 AKM Meadville Business Overview
 - 6.23.3 AKM Meadville IC Package Substrates Production, Value and Gross Margin (2021-2026)
 - 6.23.4 AKM Meadville IC Package Substrates Product Portfolio
 - 6.23.5 AKM Meadville Recent Developments
- 6.24 Victory Giant Technology
 - 6.24.1 Victory Giant Technology Company Information
 - 6.24.2 Victory Giant Technology Business Overview
 - 6.24.3 Victory Giant Technology IC Package Substrates Production, Value and Gross Margin (2021-2026)
 - 6.24.4 Victory Giant Technology IC Package Substrates Product Portfolio
 - 6.24.5 Victory Giant Technology Recent Developments

7 Global IC Package Substrates Production by Region

- 7.1 Global IC Package Substrates Production by Region: 2021 VS 2025 VS 2032
- 7.2 Global IC Package Substrates Production by Region (2021-2032)
 - 7.2.1 Global IC Package Substrates Production by Region (2021-2026)
 - 7.2.2 Global IC Package Substrates Production Forecast by Region (2027-2032)
- 7.3 Global IC Package Substrates Production by Region: 2021 VS 2025 VS 2032
- 7.4 Global IC Package Substrates Production Value by Region (2021-2032)
 - 7.4.1 Global IC Package Substrates Production Value by Region (2021-2026)
 - 7.4.2 Global IC Package Substrates Production Value by Region (2027-2032)
- 7.5 Global IC Package Substrates Market Price Analysis by Region (2021-2032)
- 7.6 Regional Production Value Trends (2021-2032)
 - 7.6.1 North America IC Package Substrates Production Value (2021-2032)
 - 7.6.2 Europe IC Package Substrates Production Value (2021-2032)
 - 7.6.3 Asia-Pacific IC Package Substrates Production Value (2021-2032)
 - 7.6.4 South America IC Package Substrates Production Value (2021-2032)
 - 7.6.5 Middle East & Africa IC Package Substrates Production Value (2021-2032)

8 Global IC Package Substrates Consumption by Region

- 8.1 Global IC Package Substrates Consumption by Region: 2021 VS 2025 VS 2032
- 8.2 Global IC Package Substrates Consumption by Region (2021-2032)
 - 8.2.1 Global IC Package Substrates Consumption by Region (2021-2026)
 - 8.2.2 Global IC Package Substrates Consumption by Region (2027-2032)
- 8.3 North America
 - 8.3.1 North America IC Package Substrates Consumption Growth Rate by Country: 2021 VS 2025 VS 2032
 - 8.3.2 North America IC Package Substrates Consumption by Country (2021-2032)
 - 8.3.3 U.S.
 - 8.3.4 Canada
 - 8.3.5 Mexico
- 8.4 Europe
 - 8.4.1 Europe IC Package Substrates Consumption Growth Rate by Country: 2021 VS 2025 VS 2032

8.4.2 Europe IC Package Substrates Consumption by Country (2021-2032)

8.4.3 Germany

8.4.4 France

8.4.5 U.K.

8.4.6 Italy

8.4.7 Netherlands

8.5 Asia Pacific

8.5.1 Asia Pacific IC Package Substrates Consumption Growth Rate by Country: 2021 VS 2025 VS 2032

8.5.2 Asia Pacific IC Package Substrates Consumption by Country (2021-2032)

8.5.3 China

8.5.4 Japan

8.5.5 South Korea

8.5.6 Southeast Asia

8.5.7 India

8.5.8 Australia

8.6 South America

8.6.1 South America IC Package Substrates Consumption Growth Rate by Country: 2021 VS 2025 VS 2032

8.6.2 South America IC Package Substrates Consumption by Country (2021-2032)

8.6.3 Brazil

8.6.4 Argentina

8.6.5 Chile

8.6.6 Colombia

8.7 Middle East & Africa

8.7.1 Middle East & Africa IC Package Substrates Consumption Growth Rate by Country: 2021 VS 2025 VS 2032

8.7.2 Middle East & Africa IC Package Substrates Consumption by Country (2021-2032)

8.7.3 Egypt

8.7.4 South Africa

8.7.5 Israel

8.7.6 Türkiye

8.7.7 GCC Countries

9 Value Chain and Sales Channels Analysis

9.1 IC Package Substrates Value Chain Analysis

9.1.1 IC Package Substrates Key Raw Materials

9.1.2 Raw Materials Key Suppliers

9.1.3 Manufacturing Cost Structure

9.1.4 IC Package Substrates Production Mode & Process

9.2 IC Package Substrates Sales Channels Analysis

9.2.1 Direct Comparison with Distribution Share

9.2.2 IC Package Substrates Distributors

9.2.3 IC Package Substrates Customers

10 Concluding Insights

11 Appendix

11.1 Reasons for Doing This Study

11.2 Research Methodology

11.3 Research Process

11.4 Authors List of This Report

11.5 Data Source

11.5.1 Secondary Sources

11.5.2 Primary Sources

11.6 Disclaimer

List of Tables and Figures

List of Tables:

- Table 1: IC Package Substrates Industry Trends
- Table 2: IC Package Substrates Industry Drivers
- Table 3: IC Package Substrates Industry Opportunities and Challenges
- Table 4: IC Package Substrates Industry Restraints
- Table 5: Global IC Package Substrates Production Value by Manufacturers (US\$ Million) & (2021-2026)
- Table 6: Global IC Package Substrates Production Value Share by Manufacturers (2021-2026)
- Table 7: Global IC Package Substrates Production by Manufacturers (K Sqm) & (2021-2026)
- Table 8: Global IC Package Substrates Production Market Share by Manufacturers
- Table 9: Global IC Package Substrates Average Price (US\$/Sqm) of Manufacturers (2021-2026)
- Table 10: Global IC Package Substrates Industry Manufacturers Ranking, 2024 VS 2025 VS 2026
- Table 11: Global IC Package Substrates Key Manufacturers Manufacturing Sites & Headquarters
- Table 12: Global IC Package Substrates Manufacturers, Product Type & Application
- Table 13: Global IC Package Substrates Manufacturers Established Date
- Table 14: Global Manufacturers Market Concentration Ratio (CR5 and HHI)
- Table 15: Global IC Package Substrates by Manufacturers Type (Tier 1, Tier 2, and Tier 3) & (based on the Production Value of 2025)
- Table 16: Major Manufacturers of FC-BGA
- Table 17: Major Manufacturers of FC-CSP
- Table 18: Major Manufacturers of WB BGA
- Table 19: Major Manufacturers of WB CSP
- Table 20: Major Manufacturers of RF Module
- Table 21: Major Manufacturers of Others
- Table 22: Global IC Package Substrates Production by Type 2021 VS 2025 VS 2032 (K Sqm)
- Table 23: Global IC Package Substrates Production by Type (2021-2026) & (K Sqm)
- Table 24: Global IC Package Substrates Production by Type (2027-2032) & (K Sqm)
- Table 25: Global IC Package Substrates Production Market Share by Type (2021-2026)
- Table 26: Global IC Package Substrates Production Market Share by Type (2027-2032)
- Table 27: Global IC Package Substrates Production Value by Type 2021 VS 2025 VS 2032 (K Sqm)
- Table 28: Global IC Package Substrates Production Value by Type (2021-2026) & (K Sqm)
- Table 29: Global IC Package Substrates Production Value by Type (2027-2032) & (K Sqm)
- Table 30: Global IC Package Substrates Production Value Market Share by Type (2021-2026)
- Table 31: Global IC Package Substrates Production Value Market Share by Type (2027-2032)
- Table 32: Major Manufacturers of Smart Phone
- Table 33: Major Manufacturers of PC (tablet and Laptop)
- Table 34: Major Manufacturers of Wearable Device
- Table 35: Major Manufacturers of Others
- Table 36: Global IC Package Substrates Production by Application 2021 VS 2025 VS 2032 (K Sqm)
- Table 37: Global IC Package Substrates Production by Application (2021-2026) & (K Sqm)
- Table 38: Global IC Package Substrates Production by Application (2027-2032) & (K Sqm)
- Table 39: Global IC Package Substrates Production Market Share by Application (2021-2026)
- Table 40: Global IC Package Substrates Production Market Share by Application (2027-2032)
- Table 41: Global IC Package Substrates Production Value by Application 2021 VS 2025 VS 2032 (K Sqm)
- Table 42: Global IC Package Substrates Production Value by Application (2021-2026) & (K Sqm)
- Table 43: Global IC Package Substrates Production Value by Application (2027-2032) & (K Sqm)
- Table 44: Global IC Package Substrates Production Value Market Share by Application (2021-2026)
- Table 45: Global IC Package Substrates Production Value Market Share by Application (2027-2032)
- Table 46: Unimicron Company Information
- Table 47: Unimicron Business Overview
- Table 48: Unimicron IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 49: Unimicron IC Package Substrates Product Portfolio
- Table 50: Unimicron Recent Development
- Table 51: Ibiden Company Information
- Table 52: Ibiden Business Overview
- Table 53: Ibiden IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-

2026)

- Table 54: Ibsiden IC Package Substrates Product Portfolio
- Table 55: Ibsiden Recent Development
- Table 56: Nan Ya PCB Company Information
- Table 57: Nan Ya PCB Business Overview
- Table 58: Nan Ya PCB IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 59: Nan Ya PCB IC Package Substrates Product Portfolio
- Table 60: Nan Ya PCB Recent Development
- Table 61: Shinko Electric Industries Company Information
- Table 62: Shinko Electric Industries Business Overview
- Table 63: Shinko Electric Industries IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 64: Shinko Electric Industries IC Package Substrates Product Portfolio
- Table 65: Shinko Electric Industries Recent Development
- Table 66: Kinsus Interconnect Technology Company Information
- Table 67: Kinsus Interconnect Technology Business Overview
- Table 68: Kinsus Interconnect Technology IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 69: Kinsus Interconnect Technology IC Package Substrates Product Portfolio
- Table 70: Kinsus Interconnect Technology Recent Development
- Table 71: AT&S Company Information
- Table 72: AT&S Business Overview
- Table 73: AT&S IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 74: AT&S IC Package Substrates Product Portfolio
- Table 75: AT&S Recent Development
- Table 76: Semco Company Information
- Table 77: Semco Business Overview
- Table 78: Semco IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 79: Semco IC Package Substrates Product Portfolio
- Table 80: Semco Recent Development
- Table 81: Kyocera Company Information
- Table 82: Kyocera Business Overview
- Table 83: Kyocera IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 84: Kyocera IC Package Substrates Product Portfolio
- Table 85: Kyocera Recent Development
- Table 86: TOPPAN Company Information
- Table 87: TOPPAN Business Overview
- Table 88: TOPPAN IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 89: TOPPAN IC Package Substrates Product Portfolio
- Table 90: TOPPAN Recent Development
- Table 91: Zhen Ding Technology Company Information
- Table 92: Zhen Ding Technology Business Overview
- Table 93: Zhen Ding Technology IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 94: Zhen Ding Technology IC Package Substrates Product Portfolio
- Table 95: Zhen Ding Technology Recent Development
- Table 96: Daeduck Electronics Company Information
- Table 97: Daeduck Electronics Business Overview
- Table 98: Daeduck Electronics IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 99: Daeduck Electronics IC Package Substrates Product Portfolio
- Table 100: Daeduck Electronics Recent Development
- Table 101: ASE Material Company Information
- Table 102: ASE Material Business Overview
- Table 103: ASE Material IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 104: ASE Material IC Package Substrates Product Portfolio
- Table 105: ASE Material Recent Development
- Table 106: LG InnoTek Company Information
- Table 107: LG InnoTek Business Overview

- Table 108: LG InnoTek IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 109: LG InnoTek IC Package Substrates Product Portfolio
- Table 110: LG InnoTek Recent Development
- Table 111: Simmtech Company Information
- Table 112: Simmtech Business Overview
- Table 113: Simmtech IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 114: Simmtech IC Package Substrates Product Portfolio
- Table 115: Simmtech Recent Development
- Table 116: Shennan Circuit Company Information
- Table 117: Shennan Circuit Business Overview
- Table 118: Shennan Circuit IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 119: Shennan Circuit IC Package Substrates Product Portfolio
- Table 120: Shennan Circuit Recent Development
- Table 121: Shenzhen Fastprint Circuit Tech Company Information
- Table 122: Shenzhen Fastprint Circuit Tech Business Overview
- Table 123: Shenzhen Fastprint Circuit Tech IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 124: Shenzhen Fastprint Circuit Tech IC Package Substrates Product Portfolio
- Table 125: Shenzhen Fastprint Circuit Tech Recent Development
- Table 126: ACCESS Company Information
- Table 127: ACCESS Business Overview
- Table 128: ACCESS IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 129: ACCESS IC Package Substrates Product Portfolio
- Table 130: ACCESS Recent Development
- Table 131: Suntak Technology Company Information
- Table 132: Suntak Technology Business Overview
- Table 133: Suntak Technology IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 134: Suntak Technology IC Package Substrates Product Portfolio
- Table 135: Suntak Technology Recent Development
- Table 136: National Center for Advanced Packaging (NCAP China) Company Information
- Table 137: National Center for Advanced Packaging (NCAP China) Business Overview
- Table 138: National Center for Advanced Packaging (NCAP China) IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 139: National Center for Advanced Packaging (NCAP China) IC Package Substrates Product Portfolio
- Table 140: National Center for Advanced Packaging (NCAP China) Recent Development
- Table 141: Huizhou China Eagle Electronic Technology Company Information
- Table 142: Huizhou China Eagle Electronic Technology Business Overview
- Table 143: Huizhou China Eagle Electronic Technology IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 144: Huizhou China Eagle Electronic Technology IC Package Substrates Product Portfolio
- Table 145: Huizhou China Eagle Electronic Technology Recent Development
- Table 146: DSBJ Company Information
- Table 147: DSBJ Business Overview
- Table 148: DSBJ IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 149: DSBJ IC Package Substrates Product Portfolio
- Table 150: DSBJ Recent Development
- Table 151: Shenzhen Kinwong Electronic Company Information
- Table 152: Shenzhen Kinwong Electronic Business Overview
- Table 153: Shenzhen Kinwong Electronic IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 154: Shenzhen Kinwong Electronic IC Package Substrates Product Portfolio
- Table 155: Shenzhen Kinwong Electronic Recent Development
- Table 156: AKM Meadville Company Information
- Table 157: AKM Meadville Business Overview
- Table 158: AKM Meadville IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 159: AKM Meadville IC Package Substrates Product Portfolio
- Table 160: AKM Meadville Recent Development
- Table 161: Victory Giant Technology Company Information

- Table 162: Victory Giant Technology Business Overview
- Table 163: Victory Giant Technology IC Package Substrates Production (K Sqm), Value (US\$ Million), Price (US\$/Sqm) and Gross Margin (2021-2026)
- Table 164: Victory Giant Technology IC Package Substrates Product Portfolio
- Table 165: Victory Giant Technology Recent Development
- Table 166: Global IC Package Substrates Production by Region: 2021 VS 2025 VS 2032 (K Sqm)
- Table 167: Global IC Package Substrates Production by Region (2021-2026) & (K Sqm)
- Table 168: Global IC Package Substrates Production Market Share by Region (2021-2026)
- Table 169: Global IC Package Substrates Production Forecast by Region (2027-2032) & (K Sqm)
- Table 170: Global IC Package Substrates Production Market Share Forecast by Region (2027-2032)
- Table 171: Global IC Package Substrates Production Value Comparison by Region: 2021 VS 2025 VS 2032 (US\$ Million)
- Table 172: Global IC Package Substrates Production Value by Region (2021-2026) & (US\$ Million)
- Table 173: Global IC Package Substrates Production Value Share by Region (2021-2026)
- Table 174: Global IC Package Substrates Production Value by Region (2027-2032) & (US\$ Million)
- Table 175: Global IC Package Substrates Production Value Share by Region: (2027-2032) & (US\$ Million)
- Table 176: Global IC Package Substrates Market Average Price (US\$/Sqm) by Region (2021-2026)
- Table 177: Global IC Package Substrates Market Average Price (US\$/Sqm) by Region (2027-2032)
- Table 178: Global IC Package Substrates Consumption by Region: 2021 VS 2025 VS 2032 (K Sqm)
- Table 179: Global IC Package Substrates Consumption by Region (2021-2026) & (K Sqm)
- Table 180: Global IC Package Substrates Consumption Market Share by Region (2021-2026)
- Table 181: Global IC Package Substrates Consumption Forecasted by Region (2027-2032) & (K Sqm)
- Table 182: Global IC Package Substrates Consumption Forecasted Market Share by Region (2027-2032)
- Table 183: North America IC Package Substrates Consumption Growth Rate by Country: 2021 VS 2025 VS 2032 (K Sqm)
- Table 184: North America IC Package Substrates Consumption by Country (2021-2026) & (K Sqm)
- Table 185: North America IC Package Substrates Consumption by Country (2027-2032) & (K Sqm)
- Table 186: Europe IC Package Substrates Consumption Growth Rate by Country: 2021 VS 2025 VS 2032 (K Sqm)
- Table 187: Europe IC Package Substrates Consumption by Country (2021-2026) & (K Sqm)
- Table 188: Europe IC Package Substrates Consumption by Country (2027-2032) & (K Sqm)
- Table 189: Asia Pacific IC Package Substrates Consumption Growth Rate by Country: 2021 VS 2025 VS 2032 (K Sqm)
- Table 190: Asia Pacific IC Package Substrates Consumption by Country (2021-2026) & (K Sqm)
- Table 191: Asia Pacific IC Package Substrates Consumption by Country (2027-2032) & (K Sqm)
- Table 192: South America IC Package Substrates Consumption Growth Rate by Country: 2021 VS 2025 VS 2032 (K Sqm)
- Table 193: South America IC Package Substrates Consumption by Country (2021-2026) & (K Sqm)
- Table 194: South America IC Package Substrates Consumption by Country (2027-2032) & (K Sqm)
- Table 195: Middle East & Africa IC Package Substrates Consumption Growth Rate by Country: 2021 VS 2025 VS 2032 (K Sqm)
- Table 196: Middle East & Africa IC Package Substrates Consumption by Country (2021-2026) & (K Sqm)
- Table 197: Middle East & Africa IC Package Substrates Consumption by Country (2027-2032) & (K Sqm)
- Table 198: Key Raw Materials
- Table 199: Raw Materials Key Suppliers
- Table 200: IC Package Substrates Distributors List
- Table 201: IC Package Substrates Customers List
- Table 202: Research Programs/Design for This Report
- Table 203: Authors List of This Report
- Table 204: Secondary Sources
- Table 205: Primary Sources

List of Figures:

- Figure 1: IC Package Substrates Product Image
- Figure 2: Global IC Package Substrates Production Value (US\$ Million), 2021 VS 2025 VS 2032
- Figure 3: Global IC Package Substrates Production Value (2021-2032) & (US\$ Million)
- Figure 4: Global IC Package Substrates Production Capacity (2021-2032) & (K Sqm)
- Figure 5: Global IC Package Substrates Production (2021-2032) & (K Sqm)
- Figure 6: Global IC Package Substrates Average Price (US\$/Sqm) & (2021-2032)
- Figure 7: Global Top 5 and 10 IC Package Substrates Players Market Share by Production Value in 2025
- Figure 8: Manufacturers Type (Tier 1, Tier 2, and Tier 3): 2021 VS 2025
- Figure 9: FC-BGA Image
- Figure 10: FC-CSP Image
- Figure 11: WB BGA Image
- Figure 12: WB CSP Image
- Figure 13: RF Module Image
- Figure 14: Others Image
- Figure 15: Global IC Package Substrates Production by Type (2021 VS 2025 VS 2032) & (K Sqm)

- Figure 16: Global IC Package Substrates Production Market Share 2021 VS 2025 VS 2032
- Figure 17: Global IC Package Substrates Production Market Share by Type (2021-2032)
- Figure 18: Global IC Package Substrates Production Value by Type (2021 VS 2025 VS 2032) & (K Sqm)
- Figure 19: Global IC Package Substrates Production Value Share 2021 VS 2025 VS 2032
- Figure 20: Global IC Package Substrates Production Value Share by Type (2021-2032)
- Figure 21: Smart Phone Image
- Figure 22: PC (tablet and Laptop) Image
- Figure 23: Wearable Device Image
- Figure 24: Others Image
- Figure 25: Global IC Package Substrates Production by Application (2021 VS 2025 VS 2032) & (K Sqm)
- Figure 26: Global IC Package Substrates Production Market Share 2021 VS 2025 VS 2032
- Figure 27: Global IC Package Substrates Production Market Share by Application (2021-2032)
- Figure 28: Global IC Package Substrates Production Value by Application (2021 VS 2025 VS 2032) & (K Sqm)
- Figure 29: Global IC Package Substrates Production Value Share 2021 VS 2025 VS 2032
- Figure 30: Global IC Package Substrates Production Value Share by Application (2021-2032)
- Figure 31: Global IC Package Substrates Production by Region: 2021 VS 2025 VS 2032 (K Sqm)
- Figure 32: Global IC Package Substrates Production Market Share by Region: 2021 VS 2025 VS 2032
- Figure 33: Global IC Package Substrates Production Value Comparison by Region: 2021 VS 2025 VS 2032 (US\$ Million)
- Figure 34: Global IC Package Substrates Production Value Share by Region: 2021 VS 2025 VS 2032
- Figure 35: North America IC Package Substrates Production Value (2021-2032) & (US\$ Million)
- Figure 36: Europe IC Package Substrates Production Value (2021-2032) & (US\$ Million)
- Figure 37: Asia-Pacific IC Package Substrates Production Value (2021-2032) & (US\$ Million)
- Figure 38: South America IC Package Substrates Production Value (2021-2032) & (US\$ Million)
- Figure 39: Middle East & Africa IC Package Substrates Production Value (2021-2032) & (US\$ Million)
- Figure 40: North America IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 41: North America IC Package Substrates Consumption Market Share by Country (2021-2032)
- Figure 42: U.S. IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 43: Canada IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 44: Mexico IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 45: Europe IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 46: Europe IC Package Substrates Consumption Market Share by Country (2021-2032)
- Figure 47: Germany IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 48: France IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 49: U.K. IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 50: Italy IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 51: Netherlands IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 52: Asia Pacific IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 53: Asia Pacific IC Package Substrates Consumption Market Share by Country (2021-2032)
- Figure 54: China IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 55: Japan IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 56: South Korea IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 57: Southeast Asia IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 58: India IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 59: Australia IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 60: South America IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 61: South America IC Package Substrates Consumption Market Share by Country (2021-2032)
- Figure 62: Brazil IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 63: Argentina IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 64: Chile IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 65: Middle East & Africa IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 66: Middle East & Africa IC Package Substrates Consumption Market Share by Country (2021-2032)
- Figure 67: Egypt IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 68: South Africa IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 69: Israel IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 70: Türkiye IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 71: GCC Countries IC Package Substrates Consumption and Growth Rate (2021-2032) & (K Sqm)
- Figure 72: IC Package Substrates Value Chain
- Figure 73: Manufacturing Cost Structure
- Figure 74: IC Package Substrates Production Mode & Process
- Figure 75: Direct Comparison with Distribution Share
- Figure 76: Distributors Profiles
- Figure 77: Years Considered
- Figure 78: Research Process
- Figure 79: Key Executives Interviewed

